



# Material Composition Declaration

## EPC2010

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	10.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	9.1182	87.81	90.05	878050
	Silicon oxide	7631-86-9	0.0349	0.34		3360
	Silicon nitride	12033-89-5	0.0108	0.10		1045
	Gallium nitride	25617-97-4	0.0662	0.64		6379
	Aluminum	7429-90-5	0.0683	0.66		6573
	Aluminum nitride	24304-00-5	0.0163	0.16		1567
	Titanium	7440-32-6	0.0013	0.01		126
	Titanium nitride	25583-20-4	0.0058	0.06		555
	Copper	7440-50-8	0.0023	0.02		219
	Tungsten	7440-33-7	0.0013	0.01		123
	Polyimide		0.0262	0.25		2527
Under Bump Metal	Titanium	7440-32-6	0.0017	0.02	0.20	167
	Nickel	7440-02-0	0.0052	0.05		499
	Vanadium	7440-62-2	0.0003	0.00		25
	Copper	7440-50-8	0.0138	0.13		1328
Solder Bump	Tin	7440-31-5	0.9665	9.31	9.75	93072
	Silver	7440-22-4	0.0405	0.39		3898
	Copper	7440-50-8	0.0051	0.05		487
Sum in total:			10.4	100	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.